



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC032NE2LS		<b>Issued</b>		22. July 2019		
<b>MA#</b>		MA005344999						
<b>Package</b>		PG-TDSON-8-51		<b>Weight*</b>		101.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.303	0.30	0.30	2993	2993
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		538	
	non noble metal	iron	7439-89-6	1.090	1.08		10753	
wire	non noble metal	copper	7440-50-8	44.271	43.67	44.81	436617	448042
	noble metal	gold	7440-57-5	0.028	0.03	0.03	279	279
	encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		875
plastics	plastics	epoxy resin	-	4.083	4.03		40263	
	inorganic material	silicondioxide	60676-86-0	40.204	39.65	43.77	396505	437643
	leadfinish	non noble metal	tin	7440-31-5	1.264	1.25	1.25	12463
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.012	0.01		117	
	non noble metal	tin	7440-31-5	0.024	0.02		234	
	non noble metal	lead	7439-92-1	0.439	0.43	0.46	4329	4680
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2247	
	non noble metal	copper	7440-50-8	9.250	9.12	9.35	91227	93614
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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